ABSTRACT OF THE DISCLOSURE:

A system for maintaining an IC-chip near a set-point temperature while electrical power dissipation in the IC-chip is varied includes a container having an op n end with a seal ring. Located in the container is at least one nozzle for spraying liquid coolant droplets on a portion of an IC-module which holds the IC-chip. This spraying of the liquid coolant occurs while the seal ring is pressed against the IC-module. Also, a pressure reducing means is coupled to the container for producing a sub-atmospheric pressure in the space between the container and the IC-module while the seal ring is pressed against the IC-module.